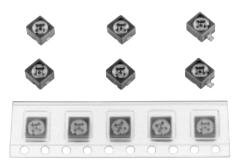
Chip Type Adjustable (pre-set) Ceramic Capacitors

Series: J

Series J are miniature in size, thin type surface mounting devices and encased in a thermosetting plastic case.

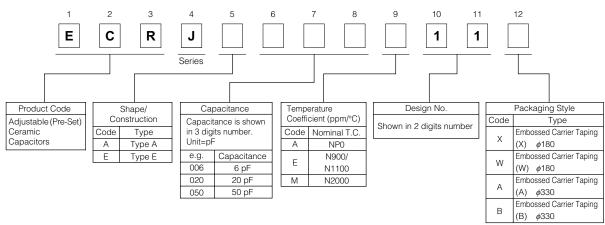
Features

- Miniature and thin type SMD: 4.0 x 4.5 x 2.7 mm
- Embossed carrier taping types are available for automatic insertion machines
- Easy reading of capacitance with colored-coded case



Recommended Applications

- Hybrid IC and micromodules
- Portable radios and cassette tape players
- VTR cameras
- Paging systems



Ratings and Characteristics

Item	Ratings		
Rated Voltage	100 VDC		
Dielectric Withstanding Voltage	220 VDC		
Insulation Resistance (at C max.)	10^4 M Ω min. at 100 VDC and 1 minute electrification		
Rotation Torque	1.47 to 9.81 mN · m		
Operating Temperature Range	–25 to +85 °C		

Part N	lumber	Capacitance (pF)		Temperature Coefficient	Q (at 1 MHz, C max)	Color	
Туре А	Type E	max.	min.	(ppm/°C)	(at 1 MHz, C max.)		
ECRJA003A11	ECRJE003A11	3 ⁺⁵⁰ %	1.7 max.	NP0±200	300 min.(10 MHz)	White	
ECRJA006A11	ECRJE006A11	6^{+50} %	2.5 max.	NP0±200		Blue	
ECRJA010A11	ECRJE010A11	10 ⁺⁵⁰ %	3.5 max.	NP0±300	500 min. (10 MHz)	White	
ECRJA020E11	ECRJE020E11	20 ⁺⁵⁰ %	5.5 max.	N900±350		Red	
ECRJA030E11	ECRJE030E11	30 ⁺⁵⁰ %	7.5 max.	N1100±450	300 min.(1 MHz)	Green	
ECRJA050M11	ECRJE050M11	50 ⁺¹⁰⁰ %	15.0 max.	N2000±600	200 min.(1 MHz)	Orange	

Design and specifications are each subject to change without notice. Ask factory for the current technical specifications before purchase and/or use. Should a safety concern arise regarding this product, please be sure to contact us immediately.

Explanation of Part Numbers

Panasonic

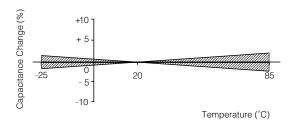
Dimensions in mm (not to scale)

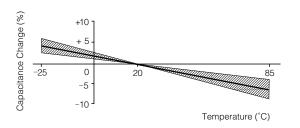
Туре	A	E
Dimensions in mm	ECRJA	
Recommended Land Layout		

Typical Characteristics Temperature Characteristics

ECRJA010A11

ECRJA020E11





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Panasonic

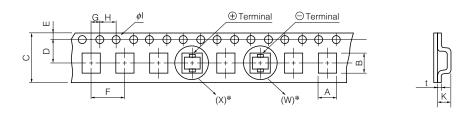
Packaging Methods

Minimum Quantity/Packing Unit

Taped Type	Packaging Style	Part Number	Dia. of reel (mm)	Minimum Packing Quantity	Packaging Quantity in Carton
х	Embossed Carrier Taping	ECRJDDDD11X	<i>ф</i> 180	700 pcs./reel	3500 pcs.
^	Embossed Carrier Taping	ECRJ IIIIIIII	<i>ø</i> 330	2500 pcs./reel	—
w	Embossed Carrier Taping	ECRJDDDDD11W	<i>ф</i> 180	700 pcs./reel	3500 pcs.
	Embossed Carrier Taping	ECRJ	<i>ø</i> 330	2500 pcs./reel	_

• Dimensions in mm (not to scale)

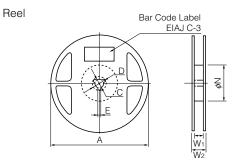
Carrier Tape



А	В	С	D	E	F	G	Н	φI	К	t
4.5±0.2	5.4±0.2	12.0±0.3	5.5±0.1	1.75±0.10	8.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1	3.2±0.2	0.30±0.05

 $\boldsymbol{\ast}$ (X) and (W) denote the package types (polarity direction)

• Dimensions in mm (not to scale)



Α	С	D	E	φN	W1	W2
180	13	21	2.0	60	13.0	15.4
330	13	22	2.5	80	13.0	19.0

Reusable Reel EIAJ ET-7200 : RRM12B

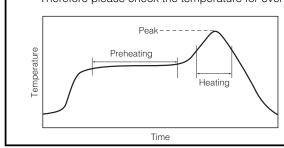
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Recommended Soldering Conditions

Recommendations and precautions are described below.

- Recommended soldering conditions for reflow
 - Please contact us for additional information when used in conditions other than those specified.
 The profile error may greatly differ depending on the measuring method.
 - The temperature varies according to the size of board or installation density.

Therefore please check the temperature for every type of board that may be used.



For lead-free soldering (Example : Sn/Ag/Cu)				
Temperature	Time			
150 °C to 180 °C	60 s to 120 s			
Above 230 °C	30 s to 40 s			
Peak max. 260 °C				
	Temperature 150 °C to 180 °C Above 230 °C			

«Recommended soldering conditions for soldering iron»

When soldering with a soldering iron, or when correcting defective soldering on parts after PWB mounting, solder following these guidelines.

- If the Adjustable (pre-set) Ceramic Capacitor is soldered exceeding the temperature range, functions or characteristics of the capacitor may degrade due to heat stress.
- In addition, the tip must not directly touch the part other than on the terminals.
- Otherwise, distortion due to thermal shock grows, and functions of the capacitor may degrade. • Solder tip temperature : 380±10 °C
- · Soldering time : 3 s max.

Design Precautions

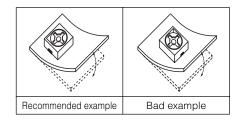
(1) When mounting Adjustable (pre-set) Ceramic Capacitor on PWB, set the capacitor in such a position and direction that it is free from the effects of PWB warping and deflection.

Mechanical stress due to PWB warping or deflection may cause the functions or characteristics of the capacitor to degrade.

① Position : Do not place a capacitor near PWB cuts or broken parts.

Ex.)

② Direction : Place the capacitors horizontal to the direction that the stress is applied.



Mounting Precautions

(1) PWB mounting

- Select ø3.8mm min. (3.8 mm if the contour is a square) for the outer diameter of the nozzle when mounting Adjustable (pre-set) Ceramic Capacitors. Air leakage may occur if the diameter is smaller than 3.8 mm.
- ② When mounting Adjustable (pre-set) Ceramic Capacitors on PWB, make sure that excessive pressure (3.92 N) or shock is not applied.

If the Adjustable (pre-set) Ceramic Capacitor is mounted with a force exceeding the specified pressure, functions of the capacitor may degrade.

- ③ Attach the product in close proximity to the PWB.
- Functions or characteristics of the capacitor may degrade if stress is concentrated at the terminals, due to load and rotation torque caused during adjustment.

(2) Flux

- ① Use flux containing less than 0.1 wt% (converted into chlorine) of halogen type substances. Do not use strong acid flux. If the halogen content is high, or strong acid flux is used the remaining flux after soldering may cause corrosion of terminals or reduction in insulation resistance.
- Amounts of Flux used during soldering.

If not enough Flux is used, insufficient fixing may occur. If the amount is too large, flux may get inside the product and may cause the characteristics or functions or the capacitor to degrade.